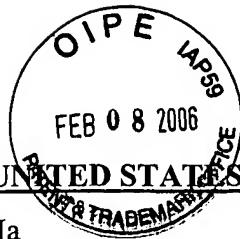


S/N 10/774,923



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Qing Ma	Examiner:	Roy Potter
Serial No.:	10/774,923	Group Art Unit:	2822
Filed:	February 9, 2004	Docket No:	884.803US2
Title	DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER STRUCTURE		
Assignee:	Intel Corporation	Customer Number:	21186

PETITION FOR A ONE-MONTH EXTENSION OF TIME

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In accordance with the provision of 37 CFR § 1.136(a), it is respectfully requested that a one-month extension of time be granted in which to respond to the Final Office Action mailed October 6, 2005, said period of response being extended from January 6, 2006 to February 6, 2006.

**Please charge Deposit Account No. 19-0743 in the amount of \$120.00 to cover the required extension fee. Please charge any additional fees or credit overpayment to deposit Account No. 19-0743.**

Respectfully Submitted  
QING MA  
By her Representatives,  
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
Attorneys for Intel Corporation  
P.O. Box 2938  
Minneapolis, Minnesota 55402  
(612) 349-9592

Date: Feb. 6, 2006 By: Ann M. McCrackin  
Ann M. McCrackin  
Reg. No: 42,858

CERTIFICATE UNDER 37 CFR § 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 6th day of February 2006.

Name: Chris Hammond Signature: Chris Hammond

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